

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6727116".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:00
L2	1	"5266833".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:47
L3	1	"5541450".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:48
L4	1	"5639695".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:48
L5	1	"6228684".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:48
L6	1	"6252300".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:48
L7	1	"6323546".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:49
L8	1	"6352923".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:49
L9	1	"6461956".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:49
L10	1	"6521485".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:49
L11	1	"6521995".PN.	USPAT; USOCR	OR	OFF	2005/04/11 09:49
L12	1	"20020079567".PN.	US-PGPUB	OR	OFF	2005/04/11 09:50
L13	3508465	(die chip ic (integrated adj circuit) semiconductor dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:00
L14	3214392	(outer edge end peripheral border) with (connector connect connecting connection terminal electrode metal column strip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:10
L15	346045	13 same 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:10

L16	10419	(trace wiring) same (pad terminal bond bonding) same 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:14
L17	2087	16 same (package packaging packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:15
L18	166	active same 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/11 10:15